Heat-Spring®

Attributes of Compressible Metal TIMs

High thermal conductivity 86W/mK

- Low bulk resistance—insensitive to BLT
- Thermal performance as low as solder at 75psi
- Surface altered to reduce contact resistance

Conformability

- Plastic deformation provides low contact resistance, especially after time zero (burn-in period)
- Inherent gap filling for co-planarity issues
- Complies with CTE mismatch

Stability Advantages

- No out-gassing
- No bake-out or pump-out
- Easy to handle
- Reclaimable/recyclable

Process Advantages:

- No reflow needed
- Clean, recyclable, and reworkable
- Unused material can be credited
- Tape & reel standard packaging

Reduce Cost and Increase Performance with Soft Metal Alloy Thermal Interface Materials (SMA-TIMs):

- Increase performance of your device through lower resistance thermal management
- Manage your assembly time with automated placement
- Increase efficiency of assembly with a clean, easy-to-place TIM
- No more goop!

Contact our engineers: **askus@indium.com**
Learn more: **www.indium.com**

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

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